

WHAT IS CLAIMED IS:

1. A chip with beveled edges, suitable for adhering onto a surface of a die pad, wherein an adhesive material is utilized to adhere the chip onto the die pad, the chip with beveled edges comprising:

an active surface having beveled edges; and

a back surface, adhering onto the surface of the die pad with the adhesive material, wherein the adhesive material covers the whole back surface of the chip and around the edges of the chip.

2. The chip of claim 1, wherein an angle between a beveled edge and the active surface of the chip is in a range of  $30^{\circ}$  to  $60^{\circ}$ .

3. The chip of claim 1, wherein an angle between a beveled edge and the active surface of the chip is  $45^{\circ}$ .

4. The chip of claim 1, wherein the adhesive material is epoxy.

5. The chip of claim 1, wherein the adhesive material is silver paste.

6. A chip with beveled edges, having an active surface and a corresponding back surface, wherein the active surface of the chip has beveled edges.

7. The chip of claim 6, wherein an angle between a beveled edge and the active surface of the chip is in a range of  $30^{\circ}$  to  $60^{\circ}$ .

8. The chip of claim 6, wherein an angle between a beveled edge and the active surface of the chip is  $45^{\circ}$ .

9. A package of a semiconductor device, the package comprising:

a carrier having a die pad and a plurality of leads;

a chip located on a surface of the die pad, wherein the chip has an active surface and a corresponding back surface, wherein the active surface has beveled edges;

an adhesive material that adheres the back surface of the chip to the surface of the die pad, wherein the adhesive material covers the whole back surface of the chip and around the sides of the chip;

a plurality of wires that electrically connect the nodes of the carrier to the active surface of the chip; and

a molding compound that covers the chip, wires and a portion of the leads.

10. The package of claim 9, wherein an angle between a beveled edge and the active surface of the chip is in a range of  $30^{\circ}$  to  $60^{\circ}$ .

11. The package of claim 9, wherein an angle between a beveled edge and the active surface of the chip is  $45^{\circ}$ .

12. The package of claim 9, wherein the adhesive material is epoxy.

13. The package of claim 9, wherein the adhesive material is silver paste.

14. A package of a semiconductor device, the package comprising:

a carrier having a die pad and a plurality of leads;

a plurality of chips, wherein one of chips is located on a top surface of the die pad and the other chips are stacked on each other, each chip has an active surface and a corresponding back surface, and the active surface has beveled edges;

an adhesive material that fills in between each chip and a space between the top surface of the die pad and one of the back surfaces of the chips, wherein the adhesive material covers the whole back surface and both sides of the chip;

a plurality of wires that electrically connect to the nodes of the carrier to the active surfaces of the chips; and

a molding compound that covers the chips, wires and a portion of leads.

15. The package of claim 14, wherein an angle between a beveled edge and the active

surface of the chip is in a range of  $30^{\circ}$  to  $60^{\circ}$ .

16. The package of claim 14, wherein an angle between a beveled edge and the active surface of the chip is  $45^{\circ}$ .

17. The package of claim 14, wherein the adhesive material is epoxy.

5 18. The package of claim 14, wherein the adhesive material is silver paste.